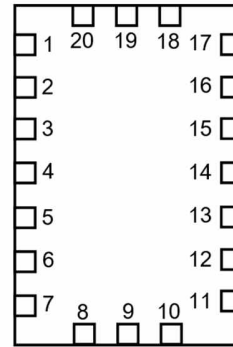


RZ/G2L SMARC SPI/CAN Level Shifter
General Description

Renesas SLG7RN45294 is a low power and small form device. The SoC is housed in a 2mm x 3mm STQFN package which is optimal for using with small devices.

Features

- Low Power Consumption
- Pb - Free / RoHS Compliant
- Halogen - Free
- STQFN - 20 Package

Pin Configuration

**STQFN-20
(Top View)**
Output Summary

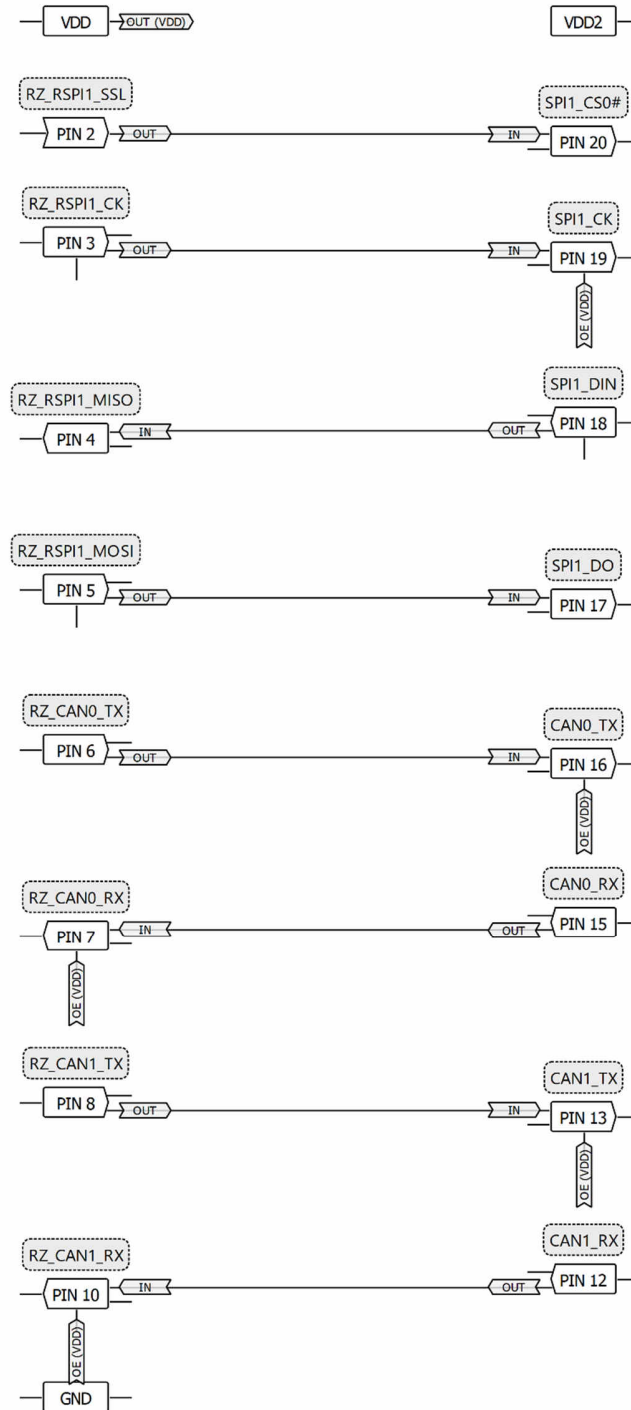
3 Outputs - Open Drain NMOS 1X
5 Outputs - Push Pull 1X

Pin name

| Pin # | Pin name | Pin # | Pin name |
|-------|---------------|-------|-----------|
| 1 | VDD | 11 | GND |
| 2 | RZ_RSPI1_SSL | 12 | CAN1_RX |
| 3 | RZ_RSPI1_CK | 13 | CAN1_TX |
| 4 | RZ_RSPI1_MISO | 14 | VDD2 |
| 5 | RZ_RSPI1_MOSI | 15 | CAN0_RX |
| 6 | RZ_CAN0_TX | 16 | CAN0_TX |
| 7 | RZ_CAN0_RX | 17 | SPI1_DO |
| 8 | RZ_CAN1_TX | 18 | SPI1_DIN |
| 9 | NC | 19 | SPI1_CK |
| 10 | RZ_CAN1_RX | 20 | SPI1_CS0# |

RZ/G2L SMARC SPI/CAN Level Shifter

Block Diagram



RZ/G2L SMARC SPI/CAN Level Shifter
Pin Configuration

| Pin # | Pin Name | Type | Pin Description | Internal Resistor |
|-------|---------------|----------------|------------------------------------|-------------------|
| 1 | VDD | PWR | Supply Voltage | -- |
| 2 | RZ_RSPI1_SSL | Digital Input | Digital Input with Schmitt trigger | floating |
| 3 | RZ_RSPI1_CK | Digital Input | Digital Input with Schmitt trigger | floating |
| 4 | RZ_RSPI1_MISO | Digital Output | Open Drain NMOS 1X | floating |
| 5 | RZ_RSPI1_MOSI | Digital Input | Digital Input with Schmitt trigger | floating |
| 6 | RZ_CAN0_TX | Digital Input | Digital Input with Schmitt trigger | floating |
| 7 | RZ_CAN0_RX | Digital Output | Open Drain NMOS 1X | floating |
| 8 | RZ_CAN1_TX | Digital Input | Digital Input with Schmitt trigger | floating |
| 9 | NC | -- | Keep Floating or Connect to GND | -- |
| 10 | RZ_CAN1_RX | Digital Output | Open Drain NMOS 1X | floating |
| 11 | GND | GND | Ground | -- |
| 12 | CAN1_RX | Digital Input | Digital Input with Schmitt trigger | floating |
| 13 | CAN1_TX | Digital Output | Push Pull 1X | floating |
| 14 | VDD2 | PWR | Supply Voltage | -- |
| 15 | CAN0_RX | Digital Input | Digital Input with Schmitt trigger | floating |
| 16 | CAN0_TX | Digital Output | Push Pull 1X | floating |
| 17 | SPI1_DO | Digital Output | Push Pull 1X | floating |
| 18 | SPI1_DIN | Digital Input | Digital Input with Schmitt trigger | floating |
| 19 | SPI1_CK | Digital Output | Push Pull 1X | floating |
| 20 | SPI1_CS0# | Digital Output | Push Pull 1X | floating |

Ordering Information

| Part Number | Package Type |
|--------------|---|
| SLG7RN45294V | 20-pin STQFN - Tape and Reel (3k units) |

RZ/G2L SMARC SPI/CAN Level Shifter
Absolute Maximum Conditions

| Parameter | Min. | Max. | Unit |
|--|-------------------------------------|-----------|------------|
| Supply Voltage on VDD relative to GND | -0.5 | 7 | V |
| Supply voltage on VDD2 relative to GND | -0.5 | VDD + 0.5 | V |
| DC Input voltage | PINs 2, 3, 4, 5, 6, 7, 8, 9, 10 | GND - 0.5 | VDD + 0.5 |
| | PINs 12, 13, 15, 16, 17, 18, 19, 20 | | VDD2 + 0.5 |
| Maximum Average or DC Current (Through pin) | Push-Pull 1x | -- | 11 |
| | OD 1x | -- | 11 |
| Current at Input Pin | -1.0 | 1.0 | mA |
| Input leakage (Absolute Value) | -- | 1000 | nA |
| Storage Temperature Range | -65 | 150 | °C |
| Junction Temperature | -- | 150 | °C |
| ESD Protection (Human Body Model) | 2000 | -- | V |
| ESD Protection (Charged Device Model) | 500 | -- | V |
| Moisture Sensitivity Level | 1 | | |

Electrical Characteristics

| Symbol | Parameter | Condition/Note | Min. | Typ. | Max. | Unit |
|------------------|---|---|------|------|------|------|
| V _{DD} | Supply Voltage | | 4.7 | 5 | 5.5 | V |
| V _{DD2} | Supply Voltage | | 1.71 | 1.8 | 5.5 | V |
| T _A | Operating Temperature | | -40 | 25 | 85 | °C |
| C _{VDD} | Capacitor Value at VDD | | -- | 0.1 | -- | μF |
| C _{IN} | Input Capacitance | | -- | 4 | -- | pF |
| I _Q | Quiescent Current | Static inputs and floating outputs | -- | 1 | -- | μA |
| V _O | Maximal Voltage Applied to any PIN in High-Impedance State | | -- | -- | VDD | V |
| I _{VDD} | Maximum Average or DC Current Through VDD Pin (Per chip side, see Note 2) | T _J = 85°C | -- | -- | 45 | mA |
| | | T _J = 110°C | -- | -- | 22 | mA |
| I _{GND} | Maximum Average or DC Current Through GND Pin (Per chip side, see Note 2) | T _J = 85°C | -- | -- | 86 | mA |
| | | T _J = 110°C | -- | -- | 41 | mA |
| V _{IH} | HIGH-Level Input Voltage PINs 2, 3, 4, 5, 6, 7, 8, 9 and 10 | Logic Input with Schmitt Trigger at VDD=5.0V | 3.34 | -- | VDD | V |
| V _{IH2} | HIGH-Level Input Voltage PINs 12, 13, 15, 16, 17, 18, 19, 20 | Logic Input with Schmitt Trigger at VDD2=1.8V | 1.28 | -- | VDD | V |
| | | Logic Input with Schmitt Trigger at VDD2=3.3V | 2.14 | -- | VDD | V |
| | | Logic Input with Schmitt Trigger at VDD2=5.0V | 3.34 | -- | VDD | V |
| V _{IL} | LOW-Level Input Voltage PINs 2, 3, 4, 5, 6, 7, 8, 9 and 10 | Logic Input with Schmitt Trigger at VDD=5.0V | 0 | -- | 1.41 | V |
| V _{IL2} | LOW-Level Input Voltage PINs 12, 13, 15, 16, 17, 18, 19, 20 | Logic Input with Schmitt Trigger at VDD2=1.8V | 0 | -- | 0.49 | V |
| | | Logic Input with Schmitt Trigger at VDD2=3.3V | 0 | -- | 0.97 | V |

RZ/G2L SMARC SPI/CAN Level Shifter

| | | | | | | |
|---------------------|---|--|-------|-------|------|----|
| | | Logic Input with Schmitt Trigger at VDD2=5.0V | 0 | -- | 1.41 | V |
| V _{OH2} | HIGH-Level Output Voltage PINs 12, 13, 15, 16, 17, 18, 19, 20 | Push-Pull 1X, I _{OH} =100μA at VDD2=1.8V | 1.69 | 1.79 | -- | V |
| | | Push-Pull 1X, I _{OH} =3mA at VDD2=3.3V | 2.74 | 3.12 | -- | V |
| | | Push-Pull 1X, I _{OH} =5mA at VDD2=5.0V | 4.15 | 4.76 | -- | V |
| V _{OL} | LOW-Level Output Voltage PINs 2, 3, 4, 5, 6, 7, 8, 9 and 10 | Open Drain NMOS 1X, I _{OL} =5mA at VDD=5.0V | -- | 0.12 | 0.16 | V |
| V _{OL2} | LOW-Level Output Voltage PINs 12, 13, 15, 16, 17, 18, 19, 20 | Push-Pull 1X, I _{OL} =100μA at VDD2=1.8V | -- | 0.01 | 0.03 | V |
| | | Push-Pull 1X, I _{OL} =3mA at VDD2=3.3V | -- | 0.13 | 0.23 | V |
| | | Push-Pull 1X, I _{OL} =5mA at VDD2=5.0V | -- | 0.19 | 0.24 | V |
| I _{OH2} | HIGH-Level Output Current (see Note 1) PINs 12, 13, 15, 16, 17, 18, 19, 20 | Push-Pull 1X, V _{OH} =VDD-0.2V at VDD2=1.8V | 1.07 | 1.70 | -- | mA |
| | | Push-Pull 1X, V _{OH} =2.4V at VDD2=3.3V | 6.05 | 12.08 | -- | mA |
| | | Push-Pull 1X, V _{OH} =2.4V at VDD2=5.0V | 22.08 | 34.04 | -- | mA |
| I _{OL} | LOW-Level Output Current (see Note 1) PINs 2, 3, 4, 5, 6, 7, 8, 9 and 10 | Open Drain NMOS 1X, V _{OL} =0.4V at VDD=5.0V | 10.82 | 17.38 | -- | mA |
| I _{OL2} | LOW-Level Output Current (see Note 1) PINs 12, 13, 15, 16, 17, 18, 19, 20 | Push-Pull 1X, V _{OL} =0.15V at VDD2=1.8V | 0.92 | 1.69 | -- | mA |
| | | Push-Pull 1X, V _{OL} =0.4V at VDD2=3.3V | 4.88 | 8.24 | -- | mA |
| | | Push-Pull 1X, V _{OL} =0.4V at VDD2=5.0V | 7.22 | 11.58 | -- | mA |
| T _{SU} | Startup Time | From VDD rising past PON _{THR} | 0.61 | 1.24 | 1.65 | ms |
| PON _{THR} | Power On Threshold | V _{DD} Level Required to Start Up the Chip | 1.41 | 1.54 | 1.66 | V |
| POFF _{THR} | Power Off Threshold | V _{DD} Level Required to Switch Off the Chip | 1.00 | 1.15 | 1.31 | V |

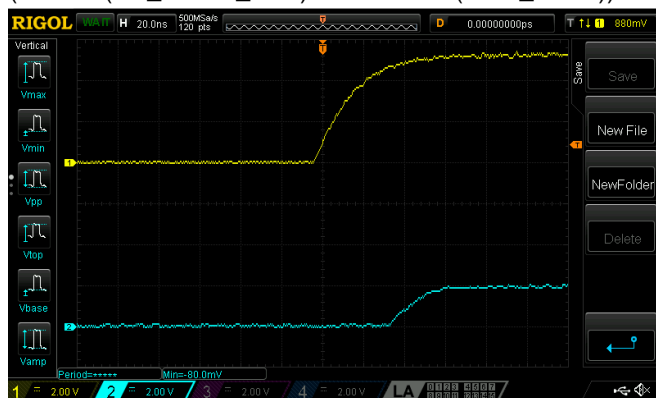
Note:

- DC or average current through any pin should not exceed value given in Absolute Maximum Conditions.
- The GreenPAK's power rails are divided in two sides. PINs 2, 3, 4, 5, 6, 7, 8, 9 and 10 are connected to one side, PINs 12, 13, 15, 16, 17, 18, 19, and 20 to another.
- Guaranteed by Design.

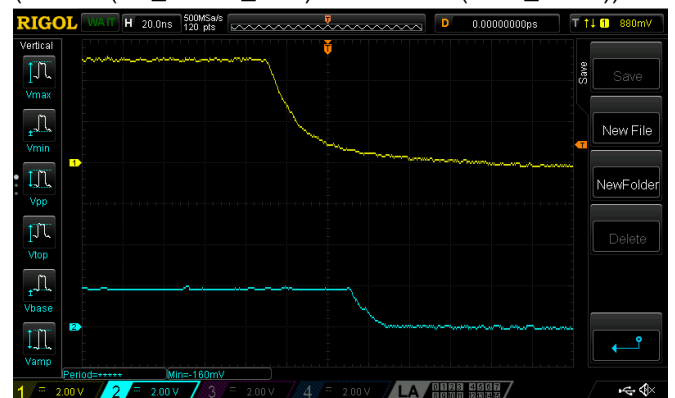
Functionality Waveforms

Channel 1 (yellow/top line) – PIN# 2 (RZ_RSPI1_SSL)
 Channel 2 (light blue/2nd line) – PIN# 20 (SPI1_CS0#)

1. Transient from Low to High
 (PIN# 2 (RZ_RSPI1_SSL) => PIN# 20 (SPI1_CS0#))

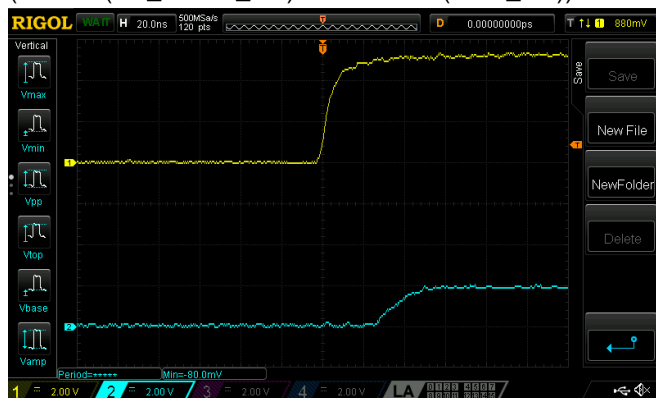


2. Transient from High to Low
 (PIN# 2 (RZ_RSPI1_SSL) => PIN# 20 (SPI1_CS0#))



Channel 1 (yellow/top line) – PIN# 3 (RZ_RSPI1_CK)
 Channel 2 (light blue/2nd line) – PIN# 19 (SPI1_CK)

3. Transient from Low to High
 (PIN# 3 (RZ_RSPI1_CK) => PIN# 19 (SPI1_CK))



4. Transient from High to Low
 (PIN# 3 (RZ_RSPI1_CK) => PIN# 19 (SPI1_CK))

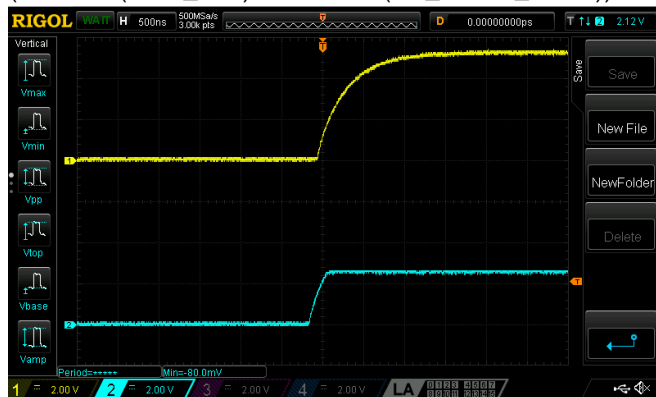


RZ/G2L SMARC SPI/CAN Level Shifter

Channel 1 (yellow/top line) – PIN# 4 (RZ_RSPI1_MISO) with external 5kΩ pull up resistor

Channel 2 (light blue/2nd line) – PIN# 18 (SPI1_DIN)

5. Transient from Low to High
(PIN# 18 (SPI1_DIN) => PIN# 4 (RZ_RSPI1_MISO))



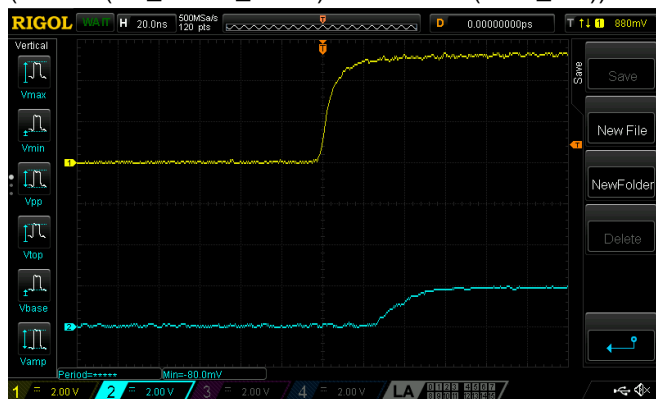
6. Transient from High to Low
(PIN# 18 (SPI1_DIN) => PIN# 4 (RZ_RSPI1_MISO))



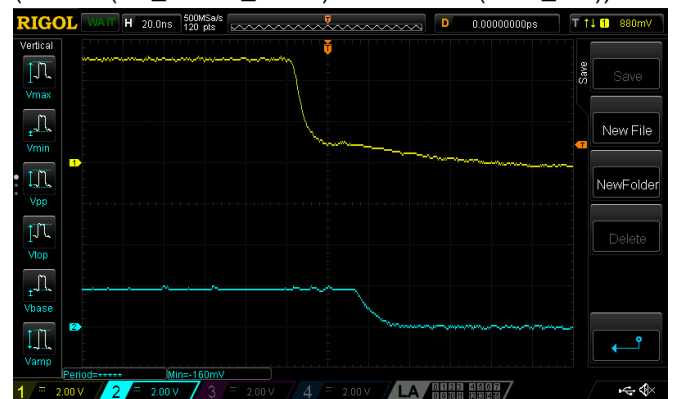
Channel 1 (yellow/top line) – PIN# 5 (RZ_RSPI1_MOSI)

Channel 2 (light blue/2nd line) – PIN# 17 (SPI1_DO)

7. Transient from Low to High
(PIN# 5 (RZ_RSPI1_MOSI) => PIN# 17 (SPI1_DO))



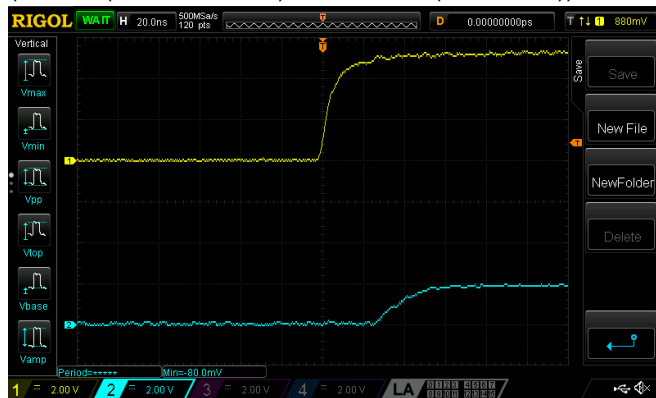
8. Transient from High to Low
(PIN# 5 (RZ_RSPI1_MOSI) => PIN# 17 (SPI1_DO))



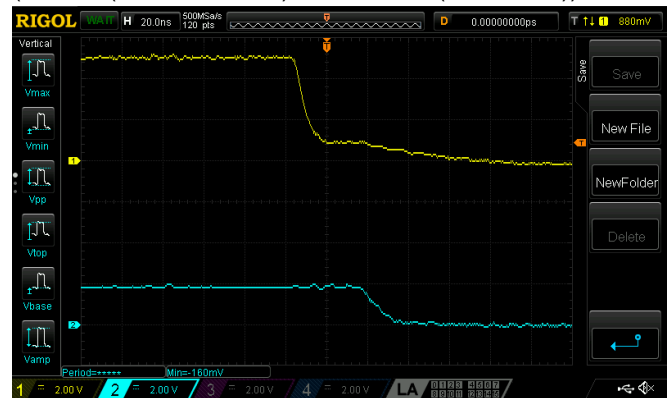
RZ/G2L SMARC SPI/CAN Level Shifter

Channel 1 (yellow/top line) – PIN# 6 (RZ_CAN0_TX)
 Channel 2 (light blue/2nd line) – PIN# 16 (CAN0_TX)

9. Transient from Low to High
 (PIN# 6 (RZ_CAN0_TX) => PIN# 16 (CAN0_TX))

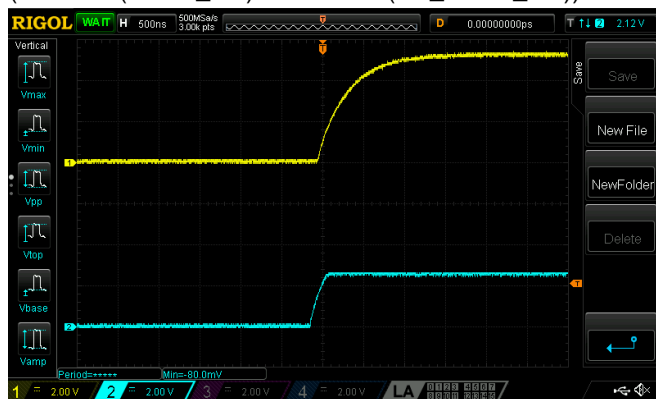


10. Transient from High to Low
 (PIN# 6 (RZ_CAN0_TX) => PIN# 16 (CAN0_TX))

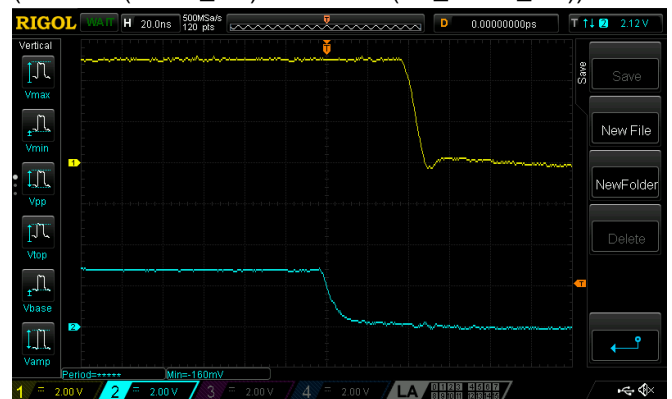


Channel 1 (yellow/top line) – PIN# 7 (RZ_CAN0_RX) with external 5kΩ pull up resistor
 Channel 2 (light blue/2nd line) – PIN# 15 (CAN0_RX)

11. Transient from Low to High
 (PIN# 15 (CAN0_RX) => PIN# 7 (RZ_CAN0_RX))



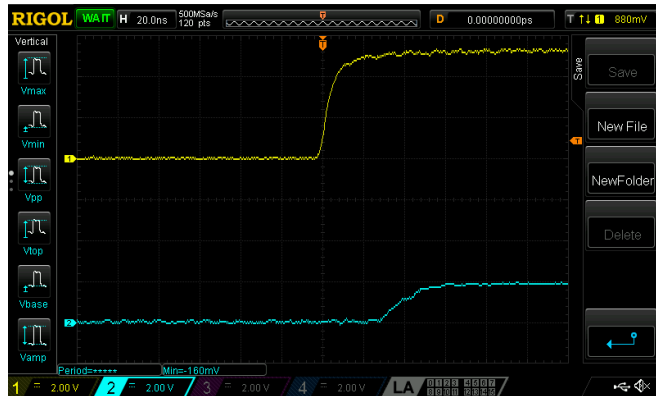
12. Transient from High to Low
 (PIN# 15 (CAN0_RX) => PIN# 7 (RZ_CAN0_RX))



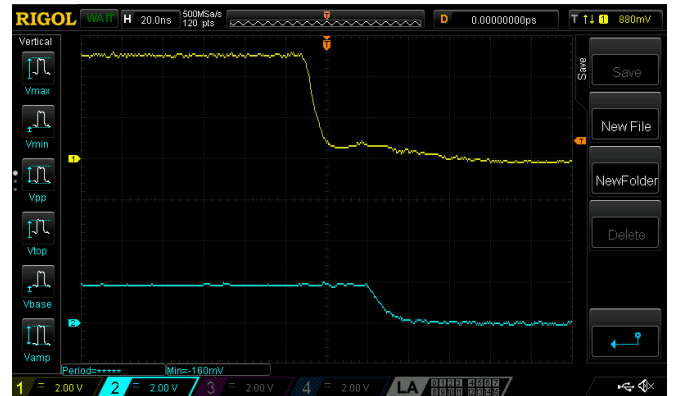
RZ/G2L SMARC SPI/CAN Level Shifter

Channel 1 (yellow/top line) – PIN# 8 (RZ_CAN1_TX)
 Channel 2 (light blue/2nd line) – PIN# 13 (CAN1_TX)

13. Transient from Low to High
 (PIN# 8 (RZ_CAN1_TX) => PIN# 13 (CAN1_TX))

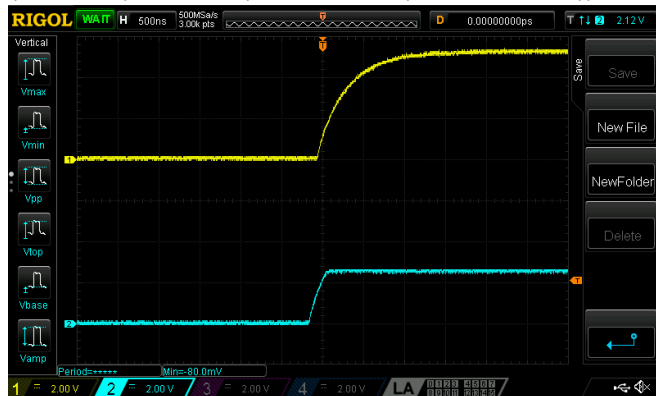


14. Transient from High to Low
 (PIN# 8 (RZ_CAN1_TX) => PIN# 13 (CAN1_TX))

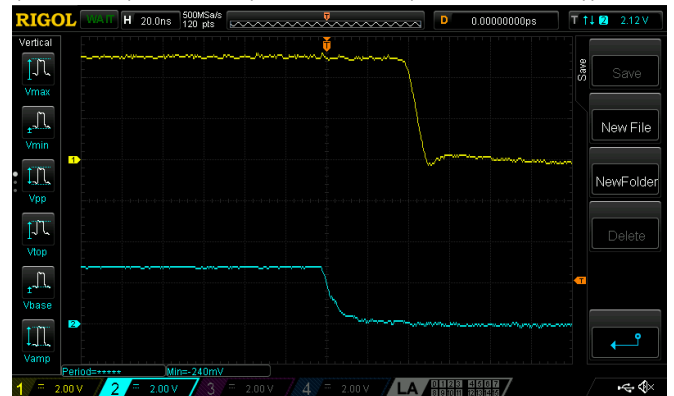


Channel 1 (yellow/top line) – PIN# 10 (RZ_CAN1_RX) with external 5kΩ pull up resistor
 Channel 2 (light blue/2nd line) – PIN# 12 (CAN1_RX)

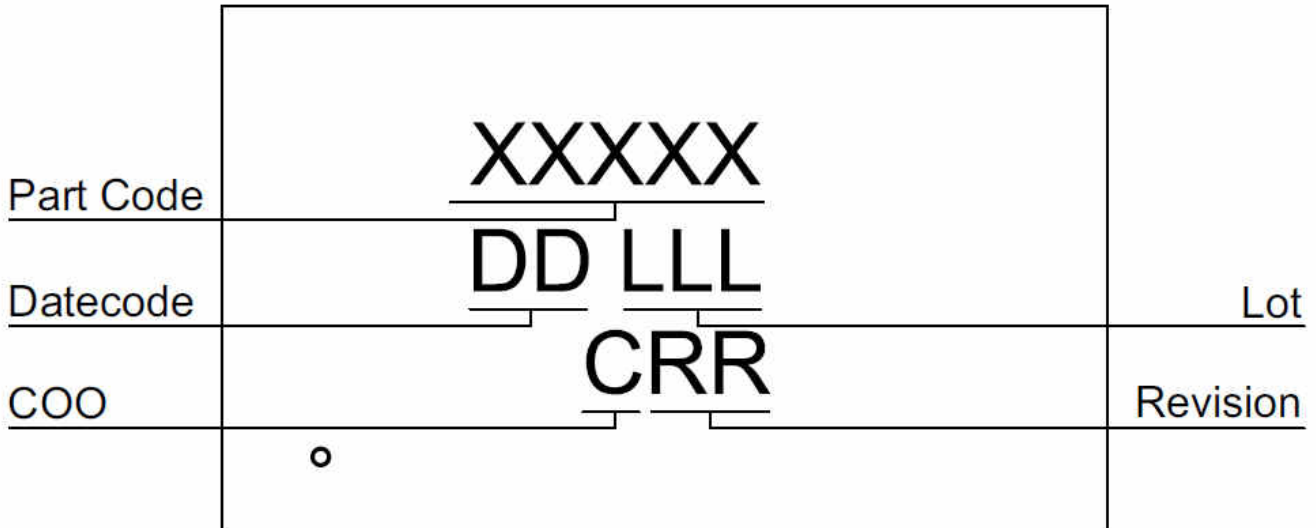
15. Transient from Low to High
 (PIN# 12 (CAN1_RX) => PIN# 10 (RZ_CAN1_RX))



16. Transient from High to Low
 (PIN# 12 (CAN1_RX) => PIN# 10 (RZ_CAN1_RX))



Package Top Marking



- XXXXX – Part ID Field: identifies the specific device configuration
- DD – Date Code Field: Coded date of manufacture
- LLL – Lot Code: Designates Lot #
- C – Assembly Site/COO: Specifies Assembly Site/Country of Origin
- RR – Revision Code: Device Revision

| Datasheet Revision | Programming Code Number | Lock Status | Checksum | Part Code | Revision | Date |
|--------------------|-------------------------|-------------|------------|-----------|----------|------------|
| 0.11 | 001 | U | 0xA06DDF4E | | | 07/11/2023 |

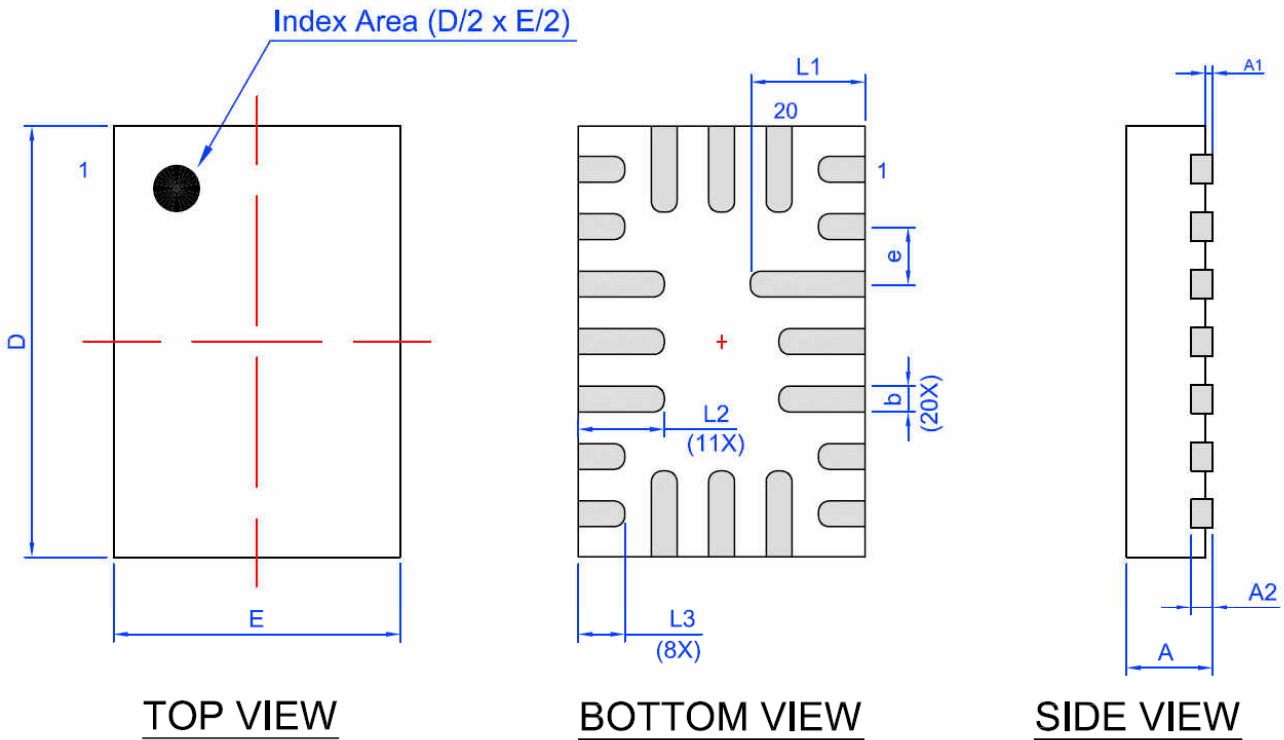
Lock coverage for this part is indicated by \checkmark , from one of the following options:

| | |
|--------------|---|
| \checkmark | Unlocked |
| | Locked for read, bits <1535:0> |
| | Locked for write, bits <1535:0> |
| | Locked for write all bits |
| | Locked for read and write bits <1535:0> |
| | Locked for read bits <1535:0> and write of all bits |

The IC security bit is locked/set for code security for production unless otherwise specified. The Programming Code Number is not changed based on the choice of locked vs. unlocked status.

Package Drawing and Dimensions

STQFN 20L 2x3mm 0.4P COL Package
JEDEC MO-220



Unit: mm

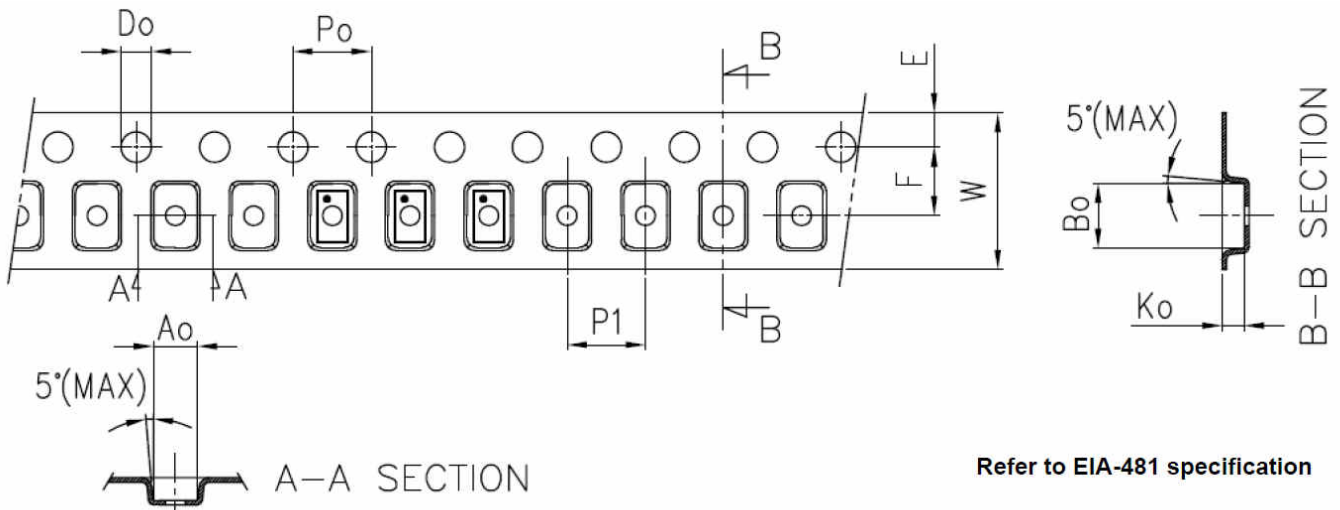
| Symbol | Min | Nom. | Max | Symbol | Min | Nom. | Max |
|--------|----------|------|-------|--------|-------|-------|-------|
| A | 0.50 | 0.55 | 0.60 | D | 2.95 | 3.00 | 3.05 |
| A1 | 0.005 | - | 0.050 | E | 1.95 | 2.00 | 2.05 |
| A2 | 0.10 | 0.15 | 0.20 | L1 | 0.75 | 0.80 | 0.85 |
| b | 0.13 | 0.18 | 0.23 | L2 | 0.55 | 0.60 | 0.65 |
| e | 0.40 BSC | | | L3 | 0.275 | 0.325 | 0.375 |

Tape and Reel Specification

| Package Type | # of Pins | Nominal Package Size [mm] | Max Units | | Reel & Hub Size [mm] | Leader (min) | | Trailer (min) | | Tape Width [mm] | Part Pitch [mm] |
|--------------------------------------|-----------|---------------------------|-----------|---------|----------------------|--------------|-------------|---------------|-------------|-----------------|-----------------|
| | | | per Reel | per Box | | Pockets | Length [mm] | Pockets | Length [mm] | | |
| STQFN 20L 2x3mm 0.4P COL | 20 | 2x3x0.55 | 3000 | 3000 | 178/60 | 100 | 400 | 100 | 400 | 8 | 4 |

Carrier Tape Drawing and Dimensions

| Package Type | Pocket BTM Length | Pocket BTM Width | Pocket Depth | Index Hole Pitch | Pocket Pitch | Index Hole Diameter | Index Hole to Tape Edge | Index Hole to Pocket Center | Tape Width |
|------------------------------------|-------------------|------------------|--------------|------------------|--------------|---------------------|-------------------------|-----------------------------|------------|
| | A0 | B0 | K0 | P0 | P1 | D0 | E | F | W |
| STQFN 20L 2x3 mm 0.4P COL | 2.2 | 3.15 | 0.76 | 4 | 4 | 1.5 | 1.75 | 3.5 | 8 |



Recommended Reflow Soldering Profile

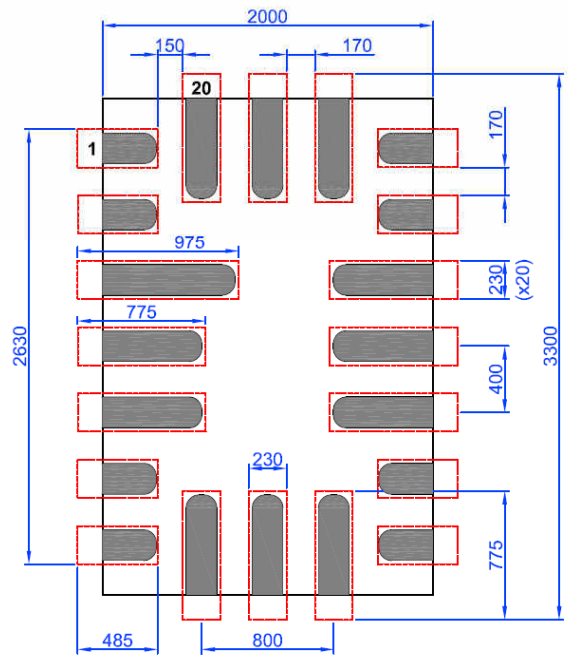
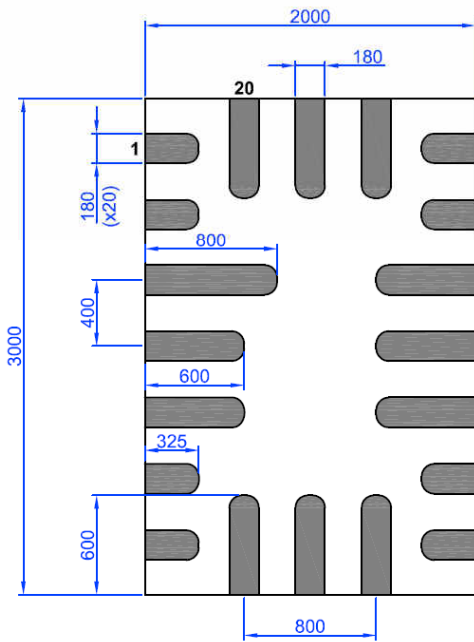
Please see IPC/JEDEC J-STD-020: latest revision for reflow profile based on package volume of 3.30 mm³ (nominal). More information can be found at www.jedec.org.

Recommended Land Pattern

 Exposed Pad
(Top View)

 Recommended Land Pattern
(Top View)

Units: μm



Datasheet Revision History

| Date | Version | Change |
|-------------|----------------|---------------------------|
| 10/07/2021 | 0.10 | New design |
| 07/11/2023 | 0.11 | Moved to Renesas template |

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